

ABSTRACT OF THE DISCLOSURE

The invention efficiently mounts substrates to back planes and accomplishes high quality signal transfer. Connectors to which N adaptor substrates are fitted and connectors to which M bus switch substrates are fitted are provided to a multi-layered back plane. Signal pin groups of the connector on the adaptor substrate side are grouped into M data paths. Signal pins of the connector on the adaptor substrate side and corresponding signal pins of the connector on the bus switch substrate side are arranged horizontally in such a fashion as to exist on the same plane (with positions in a Z direction being substantially equal). Therefore, wiring patterns for connecting corresponding signal pins can be formed substantially linearly and a large number of substrates can be efficiently mounted to a limited area.